

	SPECIFICATIONS	
STOMER	:	
AMPLE CODE	SH800480T01	3-IHC08
ASS PRODUCTION CODE	PH800480T01	3-IHC08
AMPLE VERSION	. 03	
PECIFICATIONS EDITION	006	
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Approved	D	ate: Designer
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# History of Version

Date (mm / dd / yyyy)	Ver.	Edi.	Description	Page	Design by
02/14/2017	01	001	New Drawing	-	Stephen
05/15/2017	01	002	New Sample	-	Stephen
06/30/2017	01	003	Modify Spec	4 • 10	Stephen
09/17/2019	02	004	Second Sample Create the MOSFET for BL circuit	-	Stephen
01/25/2021	02	005	Modify Spec 1.Update Firmware Version for MCU 2.New Description for Backlights 3.New Description for LCM Drawing 4.New Description for J6	4、10、14	Stephen
2/21/2024	03	006	Tertiary Sample Replace MCU		Roy



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# 1. SPECIFICATIONS

## 1.1 Features

Item	Standard Value			
Display Resolution	800 *3 (RGB) * 480 Dots			
LCD Type	a-Si TFT , Normally white , Transmissive type			
Touch Panel	Projective Capacitive Touch Panel USB HID Touch			
Screen Size(inch)	7.0 inch			
Viewing Direction	6 O'clock			
LCD Surface Treatment	Anti-Glare			
Color Configuration	R.G.B. Vertical Stripe			
Backlight Type	White LED B/L			
Interface	HDMI			
ROHS	THIS PRODUCT CONFORMS THE ROHS OF PTC Detail information please refer website :			
	http://www.powertip.com.tw/news_detail.php?Key=1&cID=1			

# **1.2 Mechanical Specifications**

Item	Standard Value	Unit
Outline Dimension	186.8 (W) * 110.56 (L) * 20.45 (H)	mm

## LCD panel

Item	Standard Value	Unit
Active Area	154.08 (W) * 85.92 (L)	mm

Note : For detailed information please refer to LCM drawing.



## 1.3 Absolute Maximum Ratings

#### Module

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply for Digital Circuit	V5v	GND=0V	-0.3	+6.0	V
Power Supply for Analog Circuit	V12V	GND=0V	-0.3	+26.0	V
Gate on – Gate off Voltage	VGH-VGL		-	+40.0	V
Gate on Voltage	VGH		-0.3	+40.0	V
Gate off Voltage	VGL		-20.0	+0.3	V
Analog Supply Voltage	AVDD		+6.5	+13.5	V
Digital Supply Voltage	DVDD		-0.3	+5.0	V
Operating Temperature	Top (Ts)	Note 1	-20	+70	°C
Storage Temperature	Tst (Ta)	Note 2	-30	+85	°C

Note 1: Ts is the temperature of panel's surface

Note 2 : Ta is the ambient temperature of samples

The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

## 1.4 DC Electrical Characteristics

#### Module

GND = 0V, Ta = 25°C

Item	Symbol	Min.	Тур.	Max.	Unit	Remark
Input Signal Voltage	V12V	V12V 11.5 12.0 1		12.5	V	-
Supply Current	IV12V	-	350	750	mA	Pattern = Full Display
	VIH	0.7*DVDD	-	DVDD	V	DVDD=3.3V
Logic Input Voltage	VIL	GND	-	0.3*DVDD	V	DVDD=3.3V



# **1.5 Optical Characteristics**

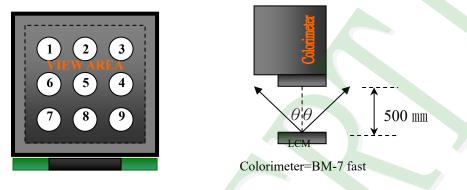
# TFT I CD Module

TFT LCD Module							Та	a=25°C
Item		Symbol	Condition	Min.	Тур.	Max.	unit	
Deenenee Time	Rise	Tr	Ta = 25°C	-	10	20		Note 2
Response Time	Fall	Tf	θX, θY = 0°	-	15	30	ms	Note 2
	Тор	θY+		40	50	-		
	Bottom	θY-	CD > 10	60	70	-	Dea	Note 1
Viewing Angle	Left	θХ-	CR ≥ 10	60	70	-	Deg.	Note 4
	Right	θX+		60	70	-		
Contrast Ratio	C	CR		400	500	-	-	Note 3
	\A/la:ta	Х	Ta = 25°C θX , θY = 0°	0.24	0.29	0.34	-	Note1
	White	Y		0.28	0.33	0.38		
	Ded	Х		0.52	0.57	0.62		
Color of CIE	Red	Y		0.30	0.35	0.40		
Coordinate (With B/L)	<b>C H G H</b>	Х		0.29	0.34	0.39		
(	Green	Y		0.54	0.59	0.64		
		Х		0.09	0.14	0.19		
	Blue	Y		0.03	0.08	0.13		
Average Brightn	ess							
Pattern=White Display (With TP)*1		IV		680	850	-	cd/m <sup>2</sup>	Note1
			V12V=12.0V PWM="High"					
Uniformity			(Duty=100%)					
(With TP)*	2	∆В		70	-	-	%	Note1



Note 1:

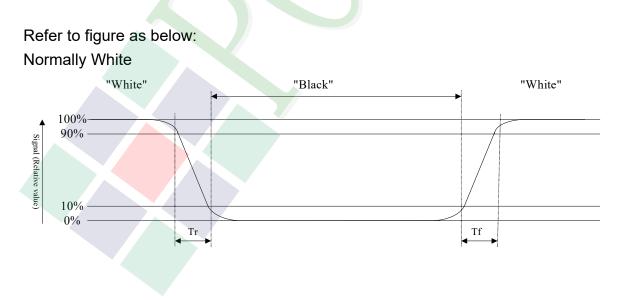
- \*1 : △B=B(min) / B(max) \* 100%
- \*2 : Measurement Condition for Optical Characteristics:
  - a : Environment: 25°C±5°C / 60±20%R.H , no wind , dark room below 10 Lux at typical lamp current and typical operating frequency.
  - b : Measurement Distance: 500 ± 50 mm  $\rightarrow$  (0= 0°)
  - c : Equipment: TOPCON BM-7 fast , (field 1°) , after 10 minutes operation.
  - d: The uncertainty of the C.I.E coordinate measurement ±0.01, Average Brightness ± 4%



To be measured at the center area of panel with a viewing cone of 1° by Topcon luminance meter BM-7, after 10 minutes operation (module)

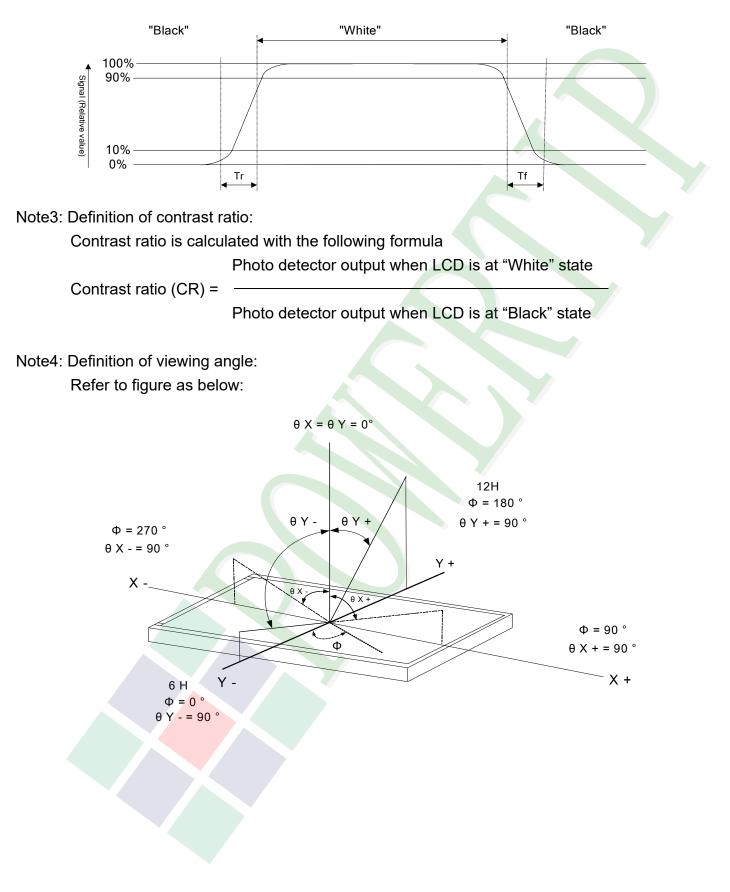
Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.





Normally Black





## **1.6 Backlight Characteristics**

## **Maximum Ratings**

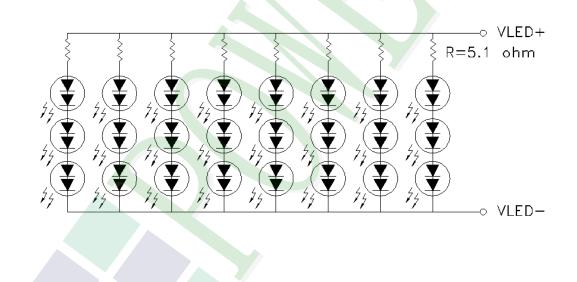
Item	Symbol	Min.	Max.	Unit	Remark
LED Forward Current	lF	35		mA	
LED Reverse Voltage	VR	10		V	One LED

Electrical / Optical Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Remark
LED Voltage	VL	I∟=140mA	14.7	18.0	19.2	V	Note1
LED life time	-		50000		1	hr	Note2

Note 1: The LED Supply Voltage is defined by the number of LED at Ta=25 °C.

Note 2: The "LED life time" is defined as the module brightness decrease to 50% original brightness at Ta=25 °C and I∟=140 mA. The LED life time could be decreased if operating I∟ is larger than 140 mA.

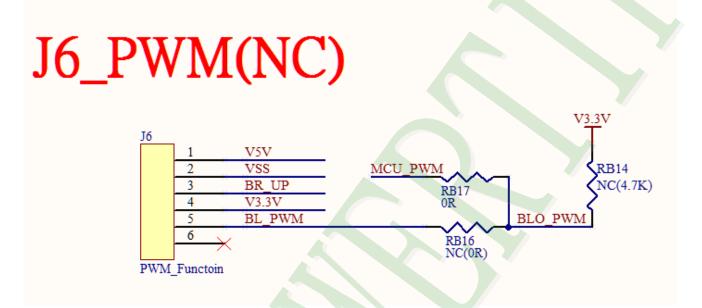




## 1.6.1 Backlight Brightness Control

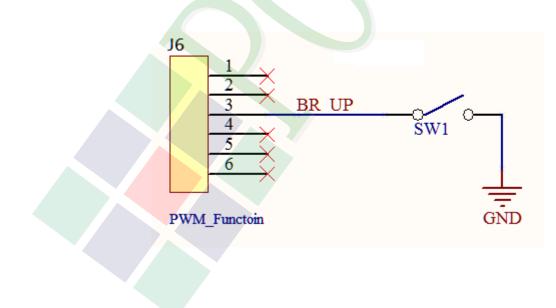
## 1.6.1.1 GPIO\_PWM (Optional)

If you want to control the display brightness, the user should connect an externally generated pulse width for pin #5 of J6. Please modify resistor RB16 and RB17 :RB17 open / RB16 short (zero-ohm resistor).



#### 1.6.1.2 Hardware Push Button Switch (Active)

Use switch to setting the backlight brightness, low active for 10 cycles to brightness control.





## 1.7 Touch Panel Characteristics

#### Features

Item	Standard Value
Touch Panel Size	7"
Touch Type	Capacitive Touch Panel
Input Method	Finger
Interface	l <sup>2</sup> C
Address	0x38 (7-bit)

#### I<sup>2</sup>C Address

10/144							
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0	1	1	1	0	0	0	R/W

Bit 0: 0 for Write / 1 for Read

## Mechanical Specifications

Item	Standard Value	Unit
Viewing Area	154.88 (W) * 86.72 (L)	mm
Number of Sensing Channel	28 * 16	

#### **Absolute Maximum Ratings**

Item	Symbol	Condition	Min.	Max.	Unit
Supply Voltage	TP_VDD	-	-0.3	+6.0	V
Operating Temperature	Тор	-	-20	+70	°C
Storage Temperature	Тзт	-	-30	+80	°C

#### **DC Electrical Characteristics**

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Voltage	TP_VDD	-	2.8	3.3	3.6	V
Input High Voltage	VIH	-	0.85 * TPVDD	-	-	V
Input Low Voltage	VIL	-	-	-	0.15 * TPVDD	V

## Touch Panel IC Read/Write description & Register Mapping

Reference : HYCON Touch Driver Porting Reference Guide.

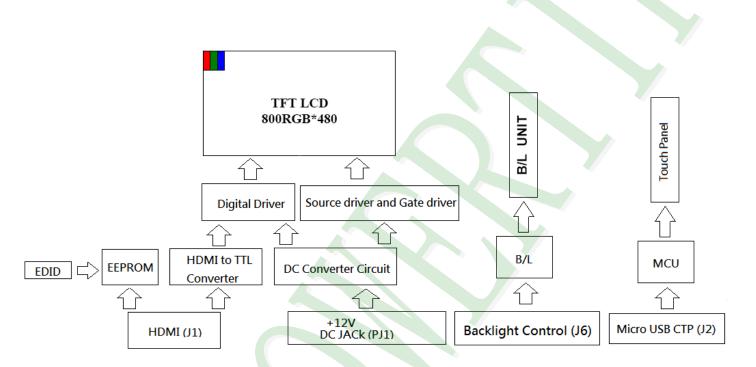


# 2. MODULE STRUCTURE

## 2.1 Counter Drawing

## 2.1.1 LCM Mechanical Diagram

- \* See Appendix
- 2.1.2 Block Diagram





# 2.2 Interface Pin Description

# 2.2.1 (J1:HDMI 1.3 A type Interface)

Pin#	Name	Description
1	TX2+	TMDS Data 2+
2	TX2 Shield	TMDS Data 2 Shield
3	TX2–	TMDS Data 2-
4	TX1+	TMDS Data 1+
5	TX1 Shield	TMDS Data 1 Shield
6	TX1–	TMDS Data 1-
7	TX0+	TMDS Data 0+
8	TX0 Shield	TMDS Data 0 Shield
9	TX0-	TMDS Data 0-
10	TXC+	TMDS Clock+
11	TXC Shield	TMDS Clock Shield
12	TXC–	TMDS Clock-
13	CEC	CEC
14	NC	No connection
15	SCL	Serial Clock for DDC
16	SDA	Serial Data for DDC
17	GND	Power Ground
18	V5V	+5V Power for HDMI
19	Hot Plug Detect	Hot Plug Detect



# 2.2.2 (PJ1:POWER DC JACK Interface)

PJ1

- - 1 **2**⊖

Hold Φ6.4mm / Center Pin Φ 2.0mm

Pin#	Name	Description
1	V12V	+12V Power
2	GND	Power Ground

## 2.2.3 (J2:Micro USB Capacitive Touch Panel Interface)

Pin#	Name	Description
1	V5V	VBus 4.75V-5.25V
2	D-	Data-
3	D+	Data+
4	ID	No Connection
5	GND	Power Ground.

## 2.2.4 (J6:Backlights Control Interface)

Pin#	Name	Description
1	V5V	Output Voltage: 4.75V~5.25V
2	GND	Power Ground.
3	BR_UP	Brightness control for customer (Note 1)
4	3V3	Output Voltage: 3.0V~3.6V
5	BL_EN	a pin as an input of PWM
6	NC	No Connection

Note 1: This function have 10 cycles for brightness control.



## 2.3 HDMI Characteristics

## 2.3.1 Signal DC&AC Characteristics

#### DC ELECTRICAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V <sub>ID</sub>	Analog input differential voltage <sup>(1)</sup>		75		1200	mV
VIC	Analog input common-mode voltage <sup>(1)</sup>		$AV_{DD} - 300$		$AV_{DD} - 37$	mV
V <sub>I(OC)</sub>	Open-circuit analog input voltage		$AV_{DD} - 10$		AV <sub>DD</sub> + 10	mV
I <sub>DD(2PIX)</sub>	Normal 2-pix/clock power supply current (2)	ODCK = 82.5 MHz, 2-pix/clock			370	mA
I <sub>PD</sub>	Power-down current (3)	PD = low			10	mA
I <sub>PDO</sub>	Output drive power-down current <sup>(3)</sup>	PDO = low		35		mA

Specified as dc characteristic with no overshoot or undershoot (1)

(2) Alternating 2-pixel black/2-pixel white pattern. ST = high,  $\overline{STAG}$  = high, QE[23:0] and QO[23:0] C<sub>L</sub> = 10 pF.

Analog inputs are open circuit (transmitter is disconnected from TFP401/401A). (3)

#### AC ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP MAX	UNIT	
VID(2)	Differential input sensitivity <sup>(1)</sup>		150	1560		
t <sub>ps</sub>	Analog input intra-pair (+ to –) differential skew (2)			0.4	t <sub>bit</sub> <sup>(3)</sup>	
t <sub>ccs</sub>	Analog input inter-pair or channel-to-channel skew <sup>(2)</sup>			1	t <sub>pix</sub> <sup>(4)</sup>	
t <sub>ijit</sub>	Worst-case differential input clock jitter tolerance <sup>(2)(5)</sup>		50		ps	
	Fall time of data and control signals <sup>(6)(7)</sup>	ST = low, C <sub>L</sub> = 5 pF		2.4	ns	
<b>t</b> <sub>f1</sub>	Fail time of data and control signals (AC)	ST = high, C <sub>L</sub> = 10 pF		1.9	115	
+	Rise time of data and control signals <sup>(6)(7)</sup>	$ST = Iow, C_L = 5 pF$		2.4	ns	
<b>Ļ</b> 1	Rise time of data and control signals. A 7	ST = high, C <sub>L</sub> = 10 pF		1.9	115	
t <sub>r2</sub>	Rise time of ODCK clock <sup>(6)</sup>	ST = low, C <sub>L</sub> = 5 pF		2.4	ns	
	Rise time of ODCK clock "	ST = high, C <sub>L</sub> = 10 pF		1.9	ns	
	Fall time of ODCK clock <sup>(6)</sup>	ST = low, C <sub>L</sub> = 5 pF		2.4	ns	
t <sub>f2</sub>		ST = high, C <sub>L</sub> = 10 pF	igh, C <sub>L</sub> = 10 pF 1			
		1 pixel/clock, PIXS = low, OCK_INV = low	1.8			
t <sub>su1</sub>	Setup time, data and control signal to falling edge of ODCK	2 pixel/clock, PIXS = high, STAG = high, OCK_INV = low	3.8		ns	
		2 pixel and STAG, PIXS = high, STAG = low, OCK_INV = low	0.7			
		1 pixel/clock, PIXS = low, OCK_INV = low	0.6			
t <sub>h1</sub>	Hold time, data and control signal to falling edge of ODCK	2 pixel and STAG, PIXS = high, STAG = low, OCK_INV = low	2.5		ns	
		2 pixel/clock, PIXS = high, STAG = high, OCK_INV = low	2.9			

(1) Specified as ac parameter to include sensitivity to overshoot, undershoot and reflection.

(2) By characterization

(3)

t<sub>bit</sub> is 1/10 the pixel time, t<sub>pix</sub> t<sub>pix</sub> is the pixel time defined as the period of the RxC input clock. The period of ODCK is equal to t<sub>pix</sub> in 1-pixel/clock mode or 2t<sub>pix</sub> when in 2-pixel/clock mode. (4)

Measured differentially at 50% crossing using ODCK output clock as trigger (5)

Rise and fall times measured as time between 20% and 80% of signal amplitude. (6)

(7)Data and control signals are QE[23:0], QO[23:0], DE, HSYNC, VSYNC. and CTL[3:1].



## AC ELECTRICAL CHARACTERISTICS (continued)

over recommended operating free-air temperature range (unless otherwise noted)

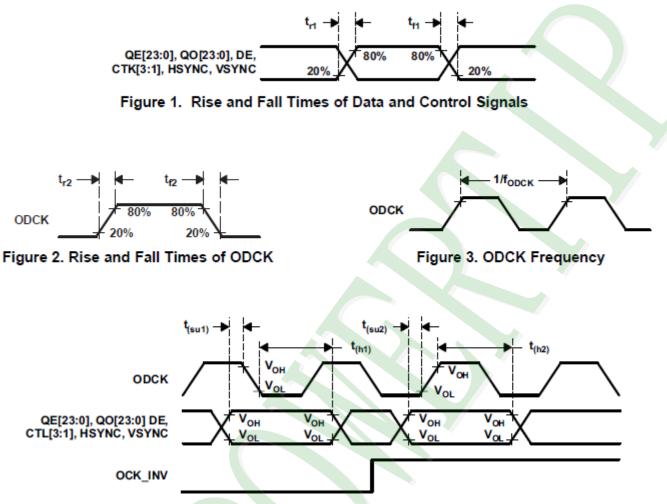
	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
		1 pixel/clock, PIXS = low, OCK_INV = high	2.1			
t <sub>su2</sub>	Setup time, data and control signal to rising edge of ODCK	2 pixel/clock, PIXS = high, STAG = high, OCK_INV = high	4			ns
		2 pixel and STAG, PIXS = high, STAG = low, OCK_INV = high	1.5			
		1 pixel/clock, PIXS = low, OCK_INV = high	0.5			
t <sub>h2</sub>	Hold time, data and control signal to rising edge of ODCK	2 pixel and STAG, PIXS = high, STAG = low, OCK_INV = high	2.4			ns
		2 pixel/clock, PIXS = high, STAG = high, OCK_INV = high	2.1			
÷	ODCK frequency	PIX = low (1-PIX/CLK)	25		165	MHz
fodck	ODCK frequency	PIX = high (2-PIX/CLK)	12.5		82.5	MHZ
	ODCK duty-cycle		40%	50%	60%	
t <sub>pd(PDL)</sub>	Propagation delay time from PD low to Hi-Z outputs				9	ns
t <sub>pd(PDOL)</sub>	Propagation delay time from PDO low to Hi-Z outputs				9	ns
t <sub>t(HSC)</sub>	Transition time between DE transition to SCDT low <sup>(8)</sup>			1e6		t <sub>pix</sub>
t <sub>t(FSC)</sub>	Transition time between DE transition to SCDT high <sup>(8)</sup>			1600		t <sub>pix</sub>
t <sub>d(st)</sub>	Delay time, ODCK latching edge to QE[23:0] data output	STAG = low, PIXS = high		0.25		t <sub>pix</sub>

(8) Link active or inactive is determined by amount of time detected between DE transitions. SCDT indicates link activity.



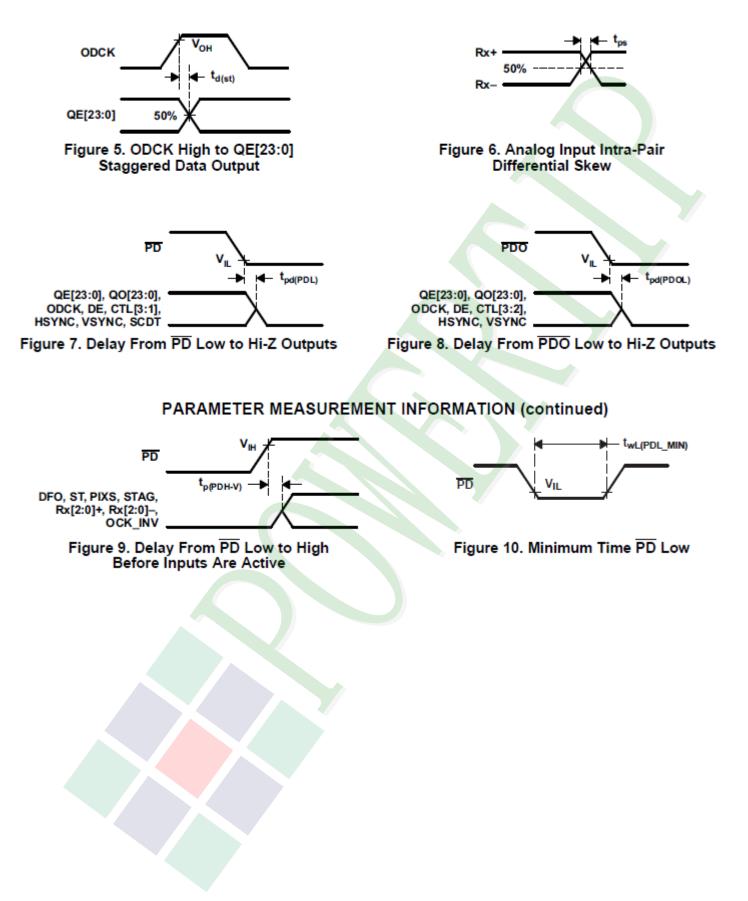
#### 2.3.2 Parameter Measurement Information



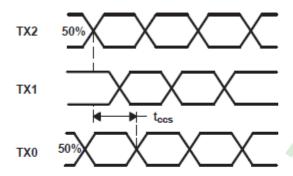


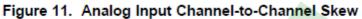
## Figure 4. Data Setup and Hold Times to Rising and Falling Edges of ODCK











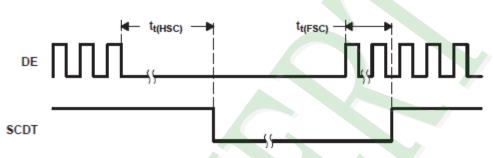


Figure 12. Time Between DE Transitions to SCDT Low and SCDT High

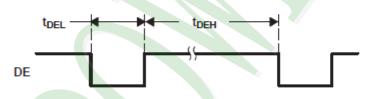
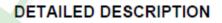
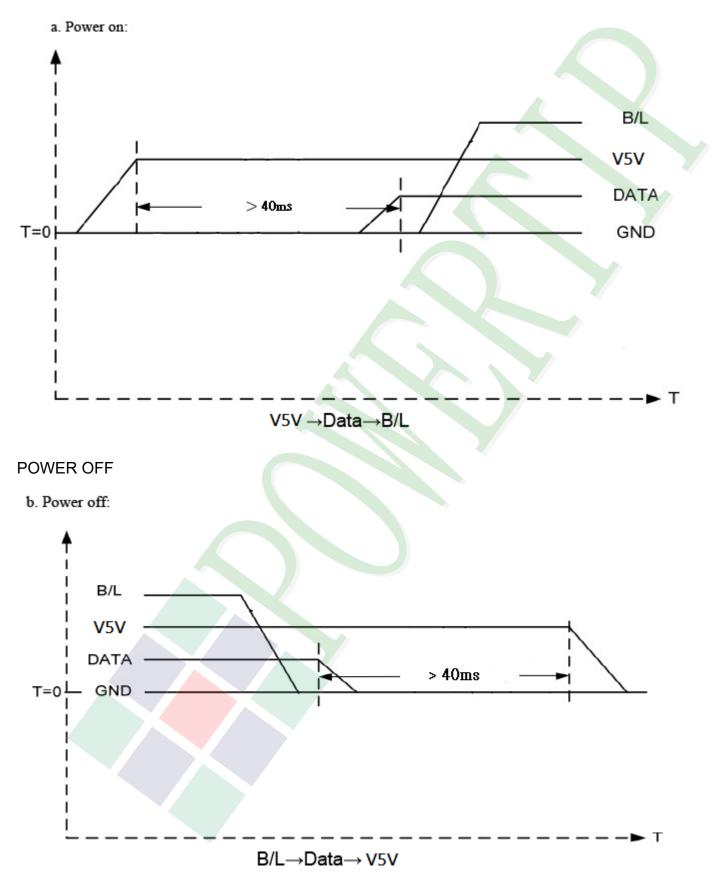


Figure 13. Minimum DE Low and Maximum DE High





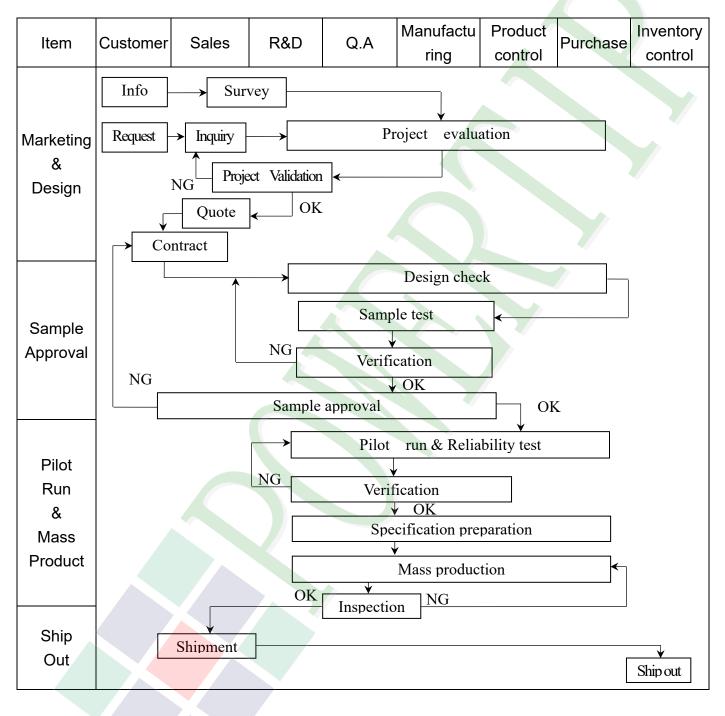
2.3.3 Power Sequence POWER ON





# **3. QUALITY ASSURANCE SYSTEM**

# 3.1 Quality Assurance Flow Chart



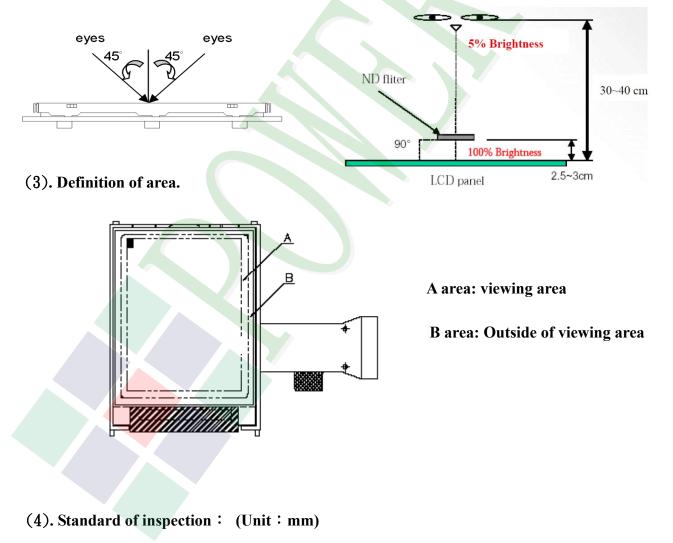


Item	Customer	Sales	R&D	Q.A	Manufact uring	Product control	Purchase	Inventory control
Sales Service	Info Analys	Claim	[	Trackin	Failure an Corrective			
Q.A Activity	1. ISO 900 3. Equipme 5. Standard	ent calibrati	ion	4	Process in Education			es

# **POWERTIP**

## **3.2. Inspection Specification**

- ◆Scope: The document shall be applied to TFT-LCD Module for 3. 5" -15″ (Ver.B01).
- ◆Inspection Standard: MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.
- **•**Equipment: Gauge, MIL-STD, Powertip Tester, Sample
- **Defect Level: Major Defect AQL: 0. 4; Minor Defect** AQL: 1.5
- **OUT Going Defect Level: Sampling.**
- **♦**Standard of the product appearance test:
  - a. Manner of appearance test:
  - (1). The test best be under 20W×2 fluorescent light(about 300lux ~500lux)
    - , and distance of view must be at 30~40 cm.
  - (2). The test direction is base on about around 45° of vertical line.





#### ◆Specification For TFT-LCD Module 3. 5" ~15" :

◆Specification For TFT-LCD Module 3. 5"~15": (Vo							
NO	Item	Criterion	Level				
	Product condition	1. 1The part number is inconsistent with work order of production.					
01		1. 2 Mixed product types.	Major				
		1. 3 Assembled in inverse direction.	Major				
02	Quantity	2. 1The quantity is inconsistent with work order of production.	Major				
03	Outline dimension	3. 1Product dimension and structure must conform to structure diagram.	Major				
		4. 1 Missing line character and icon.	Major				
		4. 2 No function or no display.	Major				
0.4	Electrical Testing	4. 3 Display malfunction.	Major				
04		4. 4 LCD viewing angle defect.					
		4. 5 Current consumption exceeds product specifications.					
		4. 6Mura cannot be seen through 5% ND filter at 50% Gray , should be judged by the viewing angle of 90 degree.	Minor				
		Item Acceptance (Q'ty)					
		$\begin{array}{c c} \text{Bright Dot} & \leq 4 \end{array}$					
	Dot defect	$Dot  Dark Dot  \leq 5$					
		DefectJoint Dot $\leq 3$					
05	(Bright dot, Dark dot)	Total $\leq 7$	Minor				
	On -display	<ul> <li>5. 1 Inspection pattern: full white, full black, Red, Green and blue screens.</li> <li>5. 2 It is defined as dot defect if defect area &gt;1/2 dot.</li> <li>5. 3 The distance between two dot defect ≥5 mm.</li> <li>5. 4 Bright dot that can not be seen through 5% ND filter.</li> </ul>	, vinior				



<b>◆</b> Spe	cification For TFT	Γ-LCD Module 3. 5″~15″:	(Ver.B01)
NO	Item	Criterion	
06	Black or white Dot, scratch, contamination Round type $\downarrow X \qquad \downarrow Y \qquad \downarrow$ $\Phi = (x+y)/2$ Line type $\downarrow L \qquad \downarrow W \qquad \downarrow$	6. 1 Round type (Non-display or display): $ Dimension (diameter : \Phi) \\ A area \\ B area \\ Total \\ 5 \\ \hline \\ B \\ \hline \\ S \\ \hline \\ \\ S \\ \hline \\ \\ S \\ \hline \\ \\ \hline \\ \\ \\ \\$	Minor
07	Polarizer Bubble	Dimension (diameter: $\Phi$ )Acceptance (Q'ty)A areaB area $\Phi \leq 0.25$ Ignore $0.25 < \Phi \leq 0.50$ 4 $0.50 < \Phi \leq 0.80$ 1Ignore $\Phi > 0.80$ $\Phi > 0.80$ 0Total5	Minor



## ◆Specification For TFT-LCD Module 3 5″~15″:

◆Specification For TFT-LCD Module 3. 5″~15″: (Ver.)				
NO	Item	Criterion		Level
		Z: The thickness of crack W	: The width of crack. : terminal length LCD side length	
		<ul><li>8.1 General glass chip:</li><li>8.1.1 Chip on panel surface and crac</li></ul>	ek between panels:	
08	The crack of glass		Y X Y ING	Minor
		Seal width	Y	
		XY	Z	
		$\leq a \qquad \begin{array}{c} Crack \ can't \ enter \\ viewing \ area \end{array}$	$\leq 1/2 t$	
		$\leq a \qquad \begin{array}{c} Crack can't exceed the \\ half of SP width. \end{array}$	$1/2 t < Z \leq 2 t$	

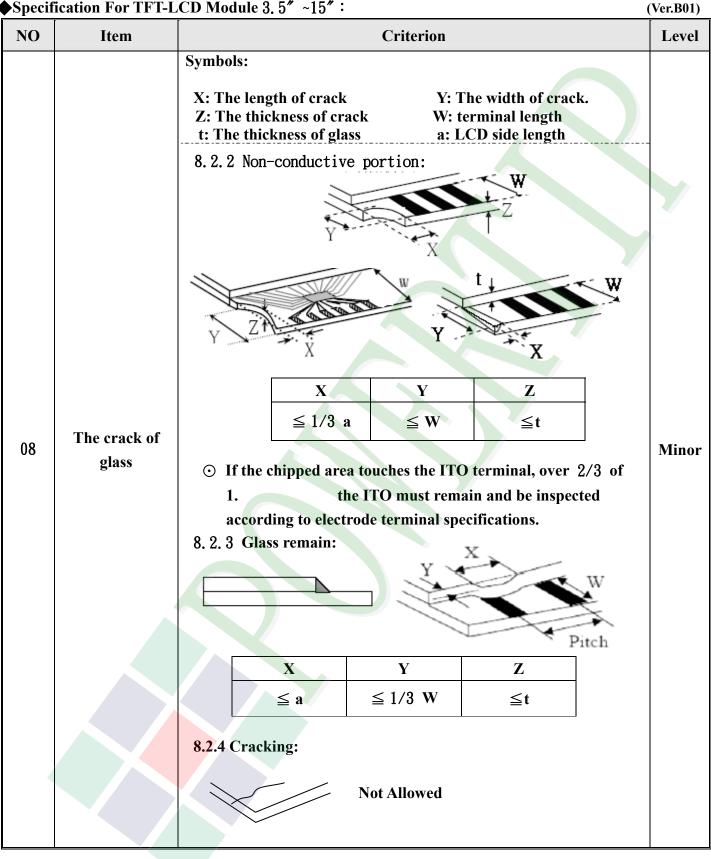


#### ◆Specification For TFT-LCD Module 3, 5″~15″:

◆Specification For TFT-LCD Module 3. 5″~15″: (Ver.B			
NO	Item	Criterion	
		Symbols :         X: The length of crack       Y: The width of crack.         Z: The thickness of crack       W: terminal length         t: The thickness of glass       a: LCD side length         8. 1. 2 Corner crack:       X         Y       Y	
		XYZ $\leq 1/5$ aCrack can't enter viewing areaZ $\leq 1/2$ t	
09	The succh of shore	$ \leq 1/5 \text{ a}  \begin{array}{ c c } \text{Crack can't exceed the} \\ \text{half of SP width.} \end{array}  1/2 \text{ t} < \text{Z}  \leq 2 \text{ t} \\ \end{array} $	Minor
08	The crack of glass	8.2 Protrusion over terminal:	Minor
		8.2.1 Chip on electrode pad:	
		X Y Z	
		Front $\leq a$ $\leq 1/2 W$ $\leq t$	
		Back $\leq a$ $\leq W$ $\leq 1/2 t$	



#### ◆Specification For TFT-LCD Module 3. 5″~15″:





#### ◆Specification For TFT-LCD Module 3. 5″~15″:

◆Specification For TFT-LCD Module 3. 5″~15″:			(Ver.B01)
NO	Item	Criterion	Level
	Backlight elements	9. 1 Backlight can't work normally.	Major
09		9. 2 Backlight doesn't light or color is wrong.	Major
		9. 3 Illumination source flickers when lit.	Major
	General appearance	10. 1Pin type < quantity < dimension must match type in structure diagram.	Major
		10. 2 No short circuits in components on PCB or FPC.	Major
10		10.3 Parts on PCB or FPC must be: no wrong parts, missing parts or excess parts.	Major
10		10. 4 Product packaging must the same as specified on packaging specification sheet.	Minor
		10. 5 The folding and peeled off in polarizer are not acceptable.	Minor
		10. 6 The PCB or FPC between B/L assembled distance(PCB or FPC ) is ≤1.5 mm.	Minor



# 4. RELIABILITY TEST

## 4.1 Reliability Test Condition

(Ver.B01)

4.1	(Ver.DUT)			
NO.	<b>TEST ITEM</b>	TEST CONDITION		
1	High Temperature Storage Test	Keep in 80 ±5℃ 240 hrs		
2	Low Temperature Storage Test	Keep in −30 ±5°C 240 hrs		
3	High Temperature / High Humidity Storage Test	Keep in 60 ℃ / 90% R.H duration for 240 hrs (Excluding the polarizer)		
4	Temperature Cycling Storage Test	$-30^{\circ}C \rightarrow +25^{\circ}C \rightarrow 80^{\circ}C \rightarrow +25^{\circ}C$ (30mins) (5mins) (30mins) (5mins) $20 \text{ Cycle}$		
5	ESD Test	Air Discharge:Contact Discharge:Apply 2 KV with 5 timesApply 250 V with 5 timesDischarge for each polarity +/-discharge for each polarity +/-1. Temperature ambiance : 15°C ~35°C2. Humidity relative : 30% ~60%3. Energy Storage Capacitance(Cs+Cd) : 150pF±10%4. Discharge Resistance(Rd) : 330 Ω±10%5. Discharge, mode of operation :Single Discharge (time between successive discharges at least 1 sec)(Tolerance if the output voltage indication : ±5%)		
6	Vibration Test (Packaged)	<ol> <li>Sine wave 10~55 Hz frequency (1 min/sweep)</li> <li>The amplitude of vibration :1.5 mm</li> <li>Each direction (X \ Y \ Z) duration for 2 Hrs</li> </ol>		
7	Drop Test (Packaged)	Packing Weight (Kg)           0 ~ 45.4           45.4 ~ 90.8           90.8 ~ 454           Over 454	122           76           61           46	

©Result Evaluation Criteria :

Under the display quality test conditions with normal operations with normal operation state. Do not change these conditions as such changes may affect practical display function. (Normal operation state)

Temperature : +20~30°C Humidity : 50~70% Atmospheric pressure : 86~106Kpa



# **5. PRECAUTION RELATING PRODUCT HANDLING**

## 5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

# 5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So, please handle it very carefully, do not touch, push or rub the exposed polarizing with anything harder than an HB pencil lead (glass, tweezers, etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is  $320 \pm 10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM
- 5.2.10 Caution!( LCM products with Capacitive Touch Panel)Strong EMI-sources such as switch-mode power supplies (SMPS) can lead to touch malfunction (e.g. ghost-touches).

Therefore, the touch needs to be thoroughly tested inside the target application.

- 5.2.11 CAUTION: Continuously displaying same static image will result in high possibility of image sticking/image burn-in effect due to TFT panel characteristic.
- 5.2.12 Double-sided tape designed to be attach with the customer's mechanical device, please follow up the rules and regulations published by the original manufacturer of double-sided tape for the attachment operation.

## 5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is  $25^{\circ}C \pm 5^{\circ}C$  and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

## 5.4 TERMS OF WARRANTY

- 5.4.1 Applicable warrant period The period is within thirteen months since the date of shipping out under normal using and storage conditions.
- 5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.

